

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seong Hun JEONG</td> <td>03/11/2013</td> </tr> <tr> <td>Ki Jun YUN</td> <td>03/11/2013</td> </tr> <tr> <td>Oh Jin JUNG</td> <td>03/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	Seong Hun JEONG	03/11/2013	Ki Jun YUN	03/11/2013	Oh Jin JUNG	03/11/2013		
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<table border="1"> <tr> <td>Name:</td> <td>Dongbu HiTek Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>90, Sudo-ro, Wonmi-gu, Bucheon-Si</td> </tr> <tr> <td>City:</td> <td>Gyeonggi-do</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> <tr> <td>Postal Code:</td> <td>420-712</td> </tr> </table>		Name:	Dongbu HiTek Co., Ltd.	Street Address:	90, Sudo-ro, Wonmi-gu, Bucheon-Si	City:	Gyeonggi-do	State/Country:	KOREA, REPUBLIC OF	Postal Code:	420-712
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 7039358473  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 571-313-7556        Email: mail@sherr-law.com        Correspondent Name: SHERR &amp; JIANG, PLLC        Address Line 1: 620 HERNDON PARKWAY        Address Line 2: SUITE 320        Address Line 4: HERNDON, VIRGINIA 20170</p>											
ATTORNEY DOCKET NUMBER:	604-0453										
NAME OF SUBMITTER:	Daniel H. Sherr										
	This document serves as an Oath/Declaration (37 CFR 1.63).										
<p>Total Attachments: 3        source=Decs-Assignments#page1.tif        source=Decs-Assignments#page2.tif        source=Decs-Assignments#page3.tif</p>											

OP \$40.00 13826912

PTO/AJA/01 (06-12) (MODIFIED)  
 Attorney Docket No.: 604-0453  
 Client Ref. No.: OPP-GZ-2012-0009-US-00

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

Title of Invention	SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME
<p>As the below named inventor, I hereby declare that:</p> <p>This declaration is directed to: <input checked="" type="checkbox"/> The attached application, or</p> <p><input type="checkbox"/> United States application or PCT international application number _____ filed on _____</p> <p>The above-identified application was made or authorized to be made by me.</p> <p>I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.</p> <p>WHEREAS, <u>Dongbu HiTek Co., Ltd.</u>, with offices at <u>98, Sudo-ro, Woonmi-gu, Bucheon-Si, Gyeonggi-do 426-712 Republic of Korea</u> (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;</p> <p>NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;</p> <p>And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;</p> <p>And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;</p> <p>And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;</p> <p>And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.</p> <p>I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.</p>	
LEGAL NAME OF INVENTOR	
Inventor: <u>Oh Jin JUNG</u>	Date: <u>2013. 3. 11</u>
Signature: <u>Oh Jin Jung</u>	

**SHERR & JIANG, PLLC**  
 620 HERNDON PARKWAY, SUITE 320  
 HERNDON, VA 20170  
 TEL: (571) 313-7556 | FAX: (703) 935-8473



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<p><b>LEGAL NAME OF INVENTOR</b></p> <p>Inventor: <u>Seong Hun JEONG</u> Date: <u>03/11/13</u></p> <p>Signature: <u>S. H. Jeong</u></p>	

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